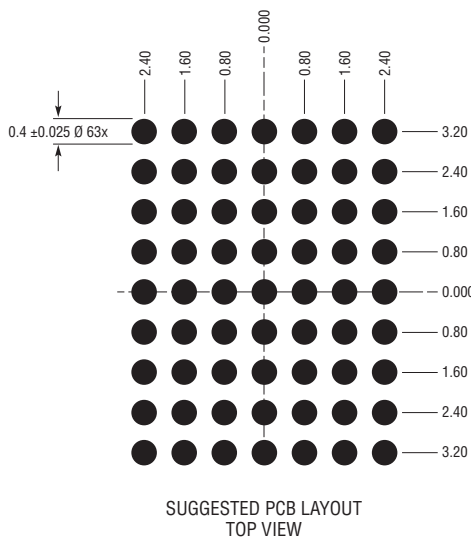
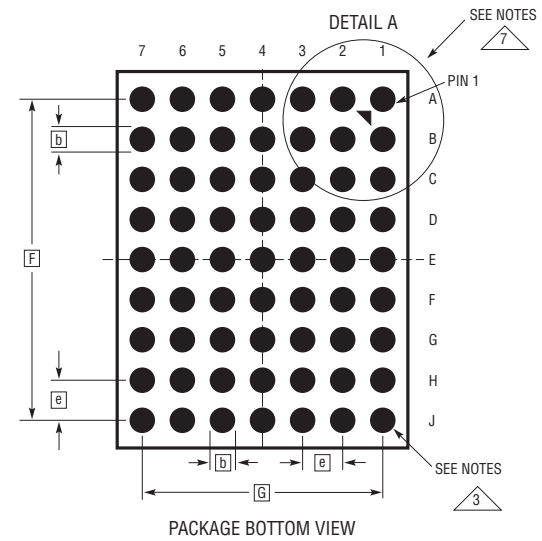
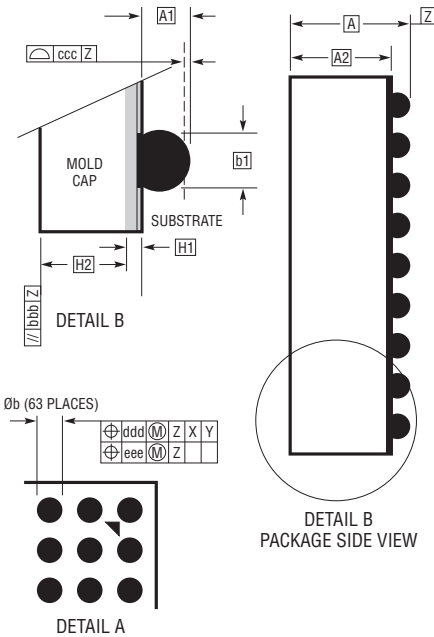
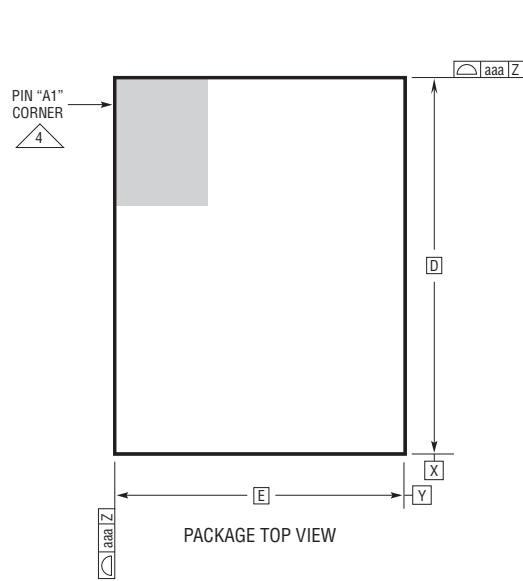


BGA Package
63-Lead (7.5mm × 6.25mm × 2.22mm)
 (Reference LTC DWG # 05-08-1988 Rev 0)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	2.07	2.22	2.37	
A1	0.35	0.40	0.45	
A2	1.72	1.82	1.92	
b	0.45	0.50	0.55	
b1	0.37	0.40	0.43	
D		7.50		
E		6.25		
e		0.80		
F		6.40		
G		4.80		
H1	0.27	0.32	0.37	
H2	1.45	1.50	1.55	
aaa			0.15	
bbb			0.10	
ccc			0.12	
ddd			0.15	
eee			0.08	

TOTAL NUMBER OF BALLS: 63

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. ALL DIMENSIONS ARE IN MILLIMETERS
 3. BALL DESIGNATION PER JESD MS-028 AND JEP95
 4. DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 5. PRIMARY DATUM -Z- IS SEATING PLANE
 6. SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu
 7. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

